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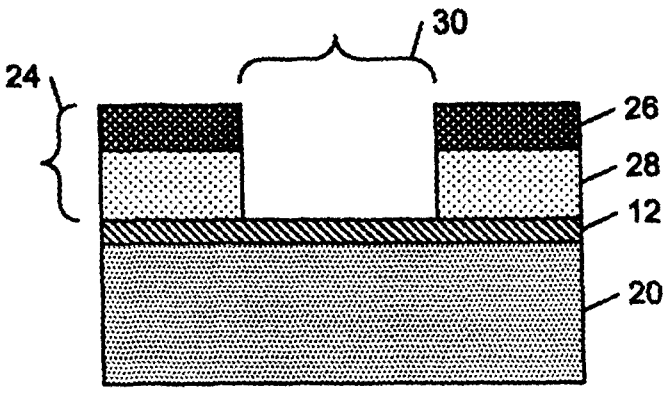
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(54) Title: FABRICATING A MOLECULAR ELECTRONIC DEVICE HAVING A PROTECTIVE BARRIER LAYER



(57) Abstract: A process of fabricating a molecular electronic device that preserves the integrity of the active molecular layer of the electronic device during processing is described. In one aspect, a barrier layer is provided to protect a molecular layer sandwiched between a bottom wire layer and a top wire layer from degradation during pattering of the top wire layer. A molecular electronic device structure and a memory system that are formed from this fabrication process are described.

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